DISCRETE SEMICONDUCTORS



Product specification

March 1993



# **BLV103**

### FEATURES

- Internal matching for an optimum wideband capability and high gain
- Emitter-ballasting resistors for optimum temperature profile
- Gold metallization ensures excellent reliability.

### DESCRIPTION

NPN silicon planar epitaxial transistor encapsulated in a 6-lead SOT171 flange envelope with a ceramic cap. It is intended for common emitter, class-AB operation in cellular radio base stations in the 960 MHz frequency band. All leads are isolated from the mounting base.

#### **PINNING - SOT171**

PIN	DESCRIPTION
1	emitter
2	emitter
3	base
4	collector
5	emitter
6	emitter

### QUICK REFERENCE DATA

RF performance at  $T_h = 25 \degree C$  in a common emitter test circuit.

MODE OF OPERATION	f	V <sub>CE</sub>	P <sub>L</sub>	G <sub>p</sub>	<sup>ղ</sup> c
	(MHz)	(V)	(W)	(dB)	(%)
c.w. class-AB	960	24	4	> 11.5	> 45

### WARNING

### Product and environmental safety - toxic materials

This product contains beryllium oxide. The product is entirely safe provided that the BeO disc is not damaged. All persons who handle, use or dispose of this product should be aware of its nature and of the necessary safety precautions. After use, dispose of as chemical or special waste according to the regulations applying at the location of the user. It must never be thrown out with the general or domestic waste.

### **PIN CONFIGURATION**



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### LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	-	50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	30	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	4	V
I <sub>C</sub>	collector current	DC or average value	-	1.25	A
P <sub>tot</sub> total power dissipation		T <sub>mb</sub> = 25 °C	-	17	W
T <sub>stg</sub>	storage temperature range		-65	150	°C
Tj	junction operating temperature		_	200	°C





Fig.3 Power/temperature derating.

#### THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
R <sub>th j-mb</sub>	from junction to mounting base	T <sub>mb</sub> = 25 °C; P <sub>dis</sub> = 17 W	10.3	K/W
R <sub>th mb-h</sub>	from mounting base to heatsink		0.4	K/W

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### CHARACTERISTICS

T<sub>j</sub> = 25 °C.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>(BR)CBO</sub>	collector-base breakdown voltage	open emitter; $I_{C} = 4 \text{ mA}$	50	-	-	V
V <sub>(BR)CEO</sub>	collector-emitter breakdown voltage	open base; I <sub>C</sub> = 30 mA	30	-	-	V
V <sub>(BR)EBO</sub>	emitter-base breakdown voltage	open collector; I <sub>E</sub> = 2 mA	4	-	-	V
I <sub>CES</sub>	collector-emitter leakage current	V <sub>BE</sub> = 0; V <sub>CE</sub> = 30 V	-	-	1	mA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 25 V; I <sub>C</sub> = 300 mA	20	40	-	
C <sub>c</sub>	collector capacitance	$V_{CB} = 25 V;$ $I_E = I_e = 0;$ f = 1  MHz	-	6.6	8	pF
C <sub>re</sub>	feedback capacitance	$V_{CE} = 25 V;$ $I_C = 20 mA;$ f = 1 MHz	-	3.5	4.5	pF





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### **APPLICATION INFORMATION**

RF performance at T<sub>h</sub> = 25 °C in a common emitter test circuit,  $R_{th mb-h} = 0.4$  K/W.

MODE OF OPERATION	f (MHz)	V <sub>CE</sub> (V)	I <sub>CQ</sub> (mA)	P <sub>L</sub> (W)	G <sub>P</sub> (dB)	η <sub>c</sub> (%)
c.w. class-AB	960	24	5	4	> 11.5 typ. 13	> 45 typ. 48
	960	26	5	4	typ. 14	typ. 50



Fig.6 Gain and efficiency as functions of load power, typical values.



Class-AB operation;  $I_{CQ} = 5 \text{ mA}$ ; f = 960 MHz.

Fig.7 Load power as a function of drive power, typical values.

#### **Ruggedness in class-AB operation**

The BLV103 is capable of withstanding a full load mismatch corresponding to VSWR = 50:1 through all phases at rated output power under the following conditions:

 $\label{eq:VCE} \begin{array}{l} \mathsf{V}_{CE} = 24 \ \mathsf{V}; \ f = 960 \ \mathsf{MHz}; \ \mathsf{T}_{h} = 25 \ ^{\circ}\mathsf{C}; \\ \mathsf{R}_{th \ mb-h} = 0.4 \ \mathsf{K/W}. \end{array}$ 

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### List of components (see test circuit)

COMPONENT	DESCRIPTION	VALUE	DIMENSIONS	CATALOGUE NO.
C1, C6, C7, C8, C15	multilayer ceramic chip capacitor	330 pF		
C2, C3, C13, C14	film dielectric trimmer	1.4 to 5.5 pF		2222 809 09001
C4, C5	multilayer ceramic chip capacitor (note 1)	5.1 pF		
C9	35 V solid aluminum capacitor	2.2 μF		2222 128 50228
C10	multilayer ceramic chip capacitor	$3 \times 100 \text{ nF}$ in parallel		
C11, C12	multiplayer ceramic chip capacitor (note 2)	6.2 pF		
L1, L12	stripline (note 3)	50 Ω	9 mm × 2.4 mm	
L2, L11	stripline (note 3)	50 Ω	23 mm × 2.4 mm	
L3	stripline (note 3)	50 Ω	16 mm × 2.4 mm	
L4	stripline (note 3)	43 Ω	$3 \text{ mm} \times 3 \text{ mm}$	
L5	3 turns enamelled 0.8 mm copper wire		int. dia. 3 mm; length 5 mm; leads 2 mm $\times$ 5 mm	
L6, L8	grade 3B Ferroxcube wideband HF choke			4312 020 36642
L7	4 turns enamelled 0.8 mm copper wire		int. dia. 4 mm; length 5 mm; leads 2 mm $\times$ 5 mm	
L9	stripline (note 3)	43 Ω	14.5 mm × 3 mm	
L10	stripline (note 3)	50 Ω	4.5 mm × 2.4 mm	
R1, R2	0.4 W metal film resistor	10 Ω		2322 151 71009

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### Notes

- 1. American Technical Ceramics (ATC) capacitor, type 100A or other capacitor of the same quality.
- 2. American Technical Ceramics (ATC) capacitor, type 100B or other capacitor of the same quality.
- 3. The striplines are on a double copper-clad printed circuit board, with PTFE fibre-glass dielectric ( $\epsilon_r = 2.2$ ); thickness  $1_{32}$  inch.



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### PACKAGE OUTLINE

### Flanged ceramic package; 2 mounting holes; 6 leads



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**SOT171A** 

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### DEFINITIONS

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
more of the limiting values of the device at these or at	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or may cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification limiting values for extended periods may affect device reliability.
Application information	

Where application information is given, it is advisory and does not form part of the specification.

### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.